DATA SHEET



BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu\, PC1060$

2.5 V HIGH PRECISION REFERENCE VOLTAGE CIRCUIT

DESCRIPTION

The μ PC1060 are high accuracy and low drift voltage references of 2.5 V output voltage.

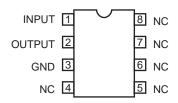
This IC can operate under wide range input voltage, and applied for 8 to 12 bits D/A converters.

★ FEATURES

High Accuracy	$Vo = 2.5 V \pm 1 \%$
• Low Temperature Coefficient	$\Delta \text{Vo}/\Delta \text{T} \le 40 \text{ ppm/}^{\circ}\text{C}$
Low Supply Current	$Icc \le 1.5 \text{ mA}$
Wide Supply Voltage Range	$4.5~V \leq V_{IN} \leq 40~V$
Low Load Regulation	REG∟ ≤ 10 mV

PIN CONFIGURATION

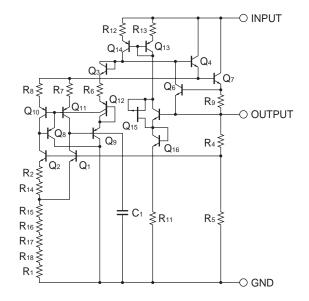
8-pin plastic DIP (7.62 mm (300)) $\mu\,\mathrm{PC}1060\mathrm{C}$



★ ORDERING INFORMATION

Part Number	Package
μ PC1060C	8-pin plastic DIP (7.62 mm (300))

EQUIVALENT CIRCUIT



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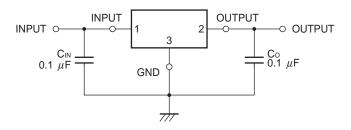
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

ABSOLUTE MAXIMUM RATINGS (TA = +25 °C, unless otherwise specified.)

Parameter	Symbol	Ratings	Unit
Input Voltage	VIN	−0.3 to +40	V
Total Power Dissipation	PT	350	mW
Operating Ambient Temperature	TA	−20 to +70	°C
Storage Temperature	T _{stg}	−55 to +125	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

TYPICAL CONNECTION



RECOMMENDED OPERATING CONDITIONS

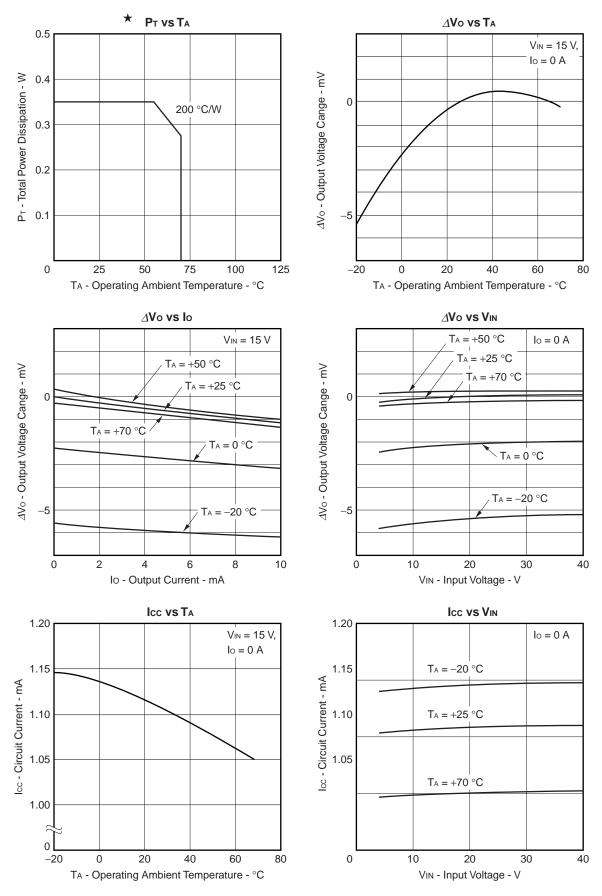
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Input Voltage	Vin	4.5		40	V
Output Current	lo	0		10	mA
Internal Power Dissipation	PD			270	mW
Operating Ambient Temperature	TA	-20		+70	°C

Caution The recommended operating range may be exceeded without causing any problems provided that the absolute maximum ratings are not exceeded. However, if the device is operated in a way that exceeds the recommended operating conditions, the margin between the actual conditions of use and the absolute maximum ratings is small, and therefore thorough evaluation is necessary. The recommended operating conditions do not imply that the device can be used with all values at their maximum values.

ELECTRICAL CHARACTERISTICS (VIN = 15 V, Io = 0 A, TA = +25 °C, unless otherwise specified.)

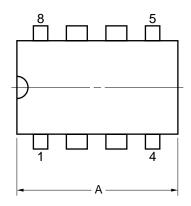
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Output Voltage	Vo		2.475	2.5	2.525	V
Output Voltage Change	ΔVo	0 °C ≤ TA ≤ 70 °C			7.0	mV
Temperature Coefficient of Output Voltage	ΔVο/ΔΤ	0 °C ≤ TA ≤ 70 °C			40	ppm/°C
Line Regulation	REGIN	15 V ≤ V _{IN} ≤ 40 V			4.5	mV
		4.5 V ≤ V _{IN} ≤ 15 V			3.0	mV
Load Regulation	REGL	0 A ≤ lo ≤ 10 mA			10	mV
Ripple Rejection	R•R	5 V ≤ V _{IN} ≤ 40 V, f = 120 Hz		90		dB
Output Noise Voltage	Vn	$4.5 \text{ V} \le \text{V}_{\text{IN}} \le 40 \text{ V}, 0 \text{ A} \le \text{Io} \le 10 \text{ mA},$ $P_{\text{T}} \le 350 \text{ mW}$		80		μ V _{p-p}
Short Circuit Current	lOshort	Vo = 0 V		17		mA
Circuit Current	Icc				1.5	mA

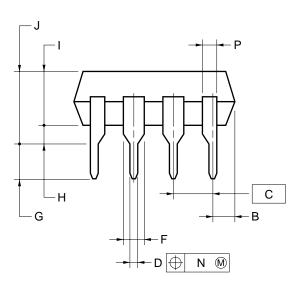
TYPICAL CHARACTERISTIC (TA = +25 °C, unless otherwise specified. Nominal)

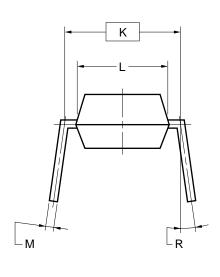


PACKAGE DRAWING

8-PIN PLASTIC DIP (7.62mm(300))







NOTES

- 1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
- 2. Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS
Α	10.16 MAX.
В	1.27 MAX.
С	2.54 (T.P.)
D	0.50±0.10
F	1.4 MIN.
G	3.2±0.3
Н	0.51 MIN.
T	4.31 MAX.
J	5.08 MAX.
K	7.62 (T.P.)
L	6.4
М	0.25+0.10
N	0.25
P	0.9 MIN.
R	0~15°

P8C-100-300B,C-2

* RECOMMENDED SOLDERING CONDITIONS

When soldering this product, it is highly recommended to observe the conditions as shown below.

If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

For more details, refer to our document "Semiconductor Device Mounting Technology Manual" (C10535E).

Type of Through-hole Device

μ PC1060C : 8-pin plastic DIP (7.62 mm (300))

Process	Conditions		
Wave soldering (only to leads)	Solder temperature: 260°C or below, Flow time: 10 seconds or less.		

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

REFERENCE DOCUMENTS

Semiconductor Device Mounting Technology Manual C10535E Semiconductor Selection Guide -Products and Packages- X13769X **NEC** μ PC1060

[MEMO]

NEC μ PC1060

[MEMO]

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 - Specific: Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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